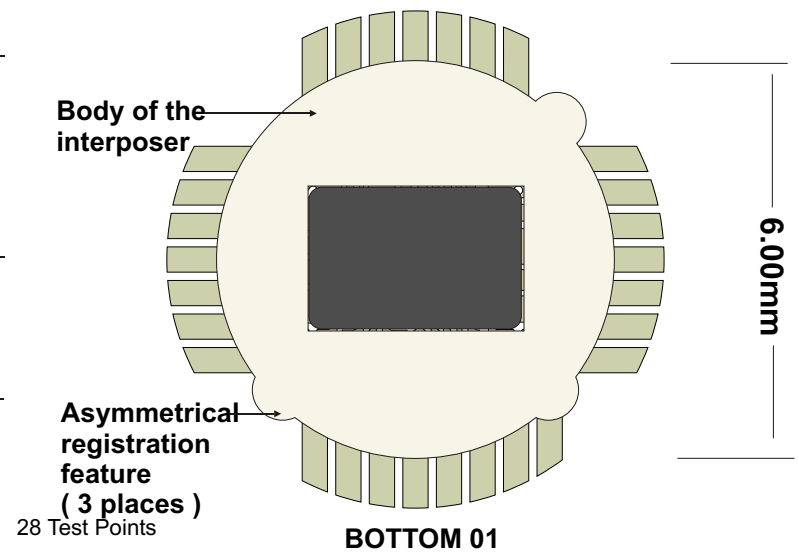
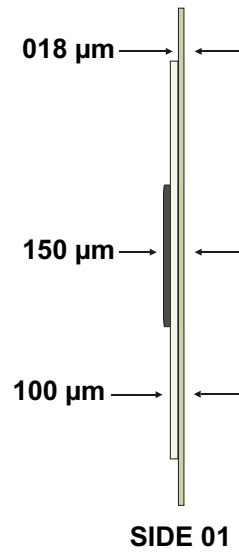
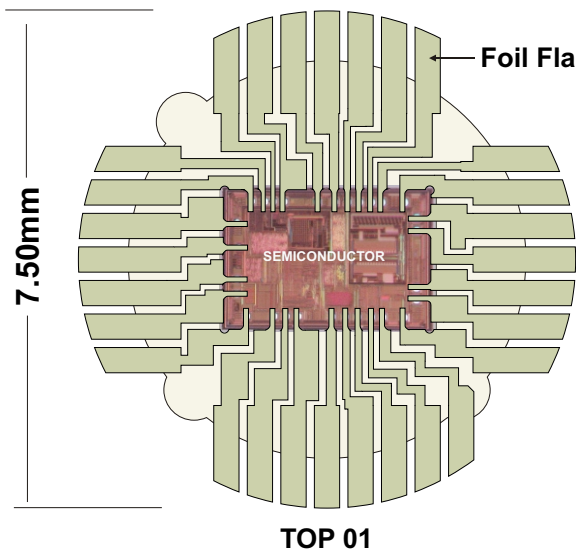
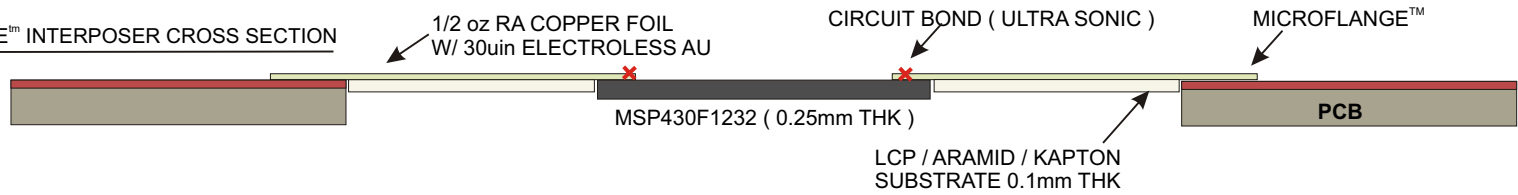


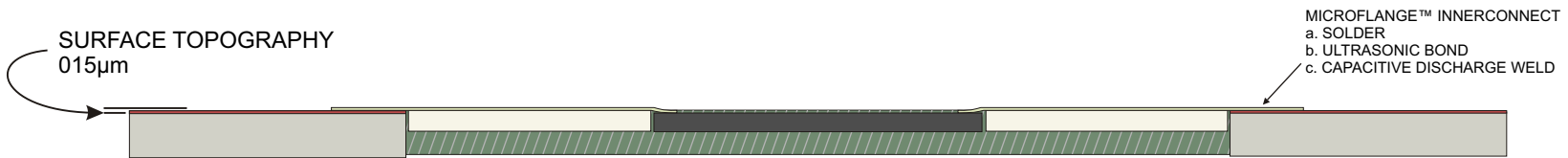
MICROFLANGE™ INTERPOSER CROSS SECTION





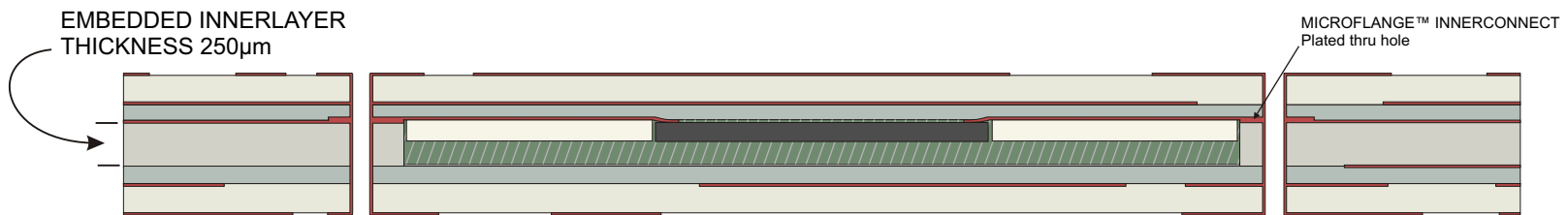
SURFACE MOUNT

A MicroFlange™ component may be placed bond side down and attached by one of several conventional mounting techniques.



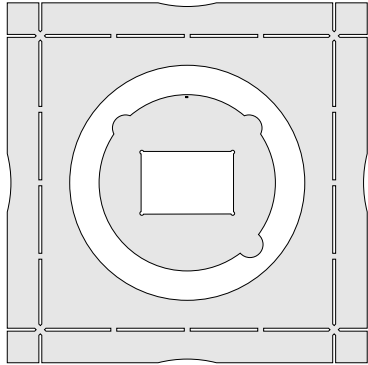
INTEGRATED

A MicroFlange™ component may be placed bond side up and recessed in the cavity of any conventional substrate material

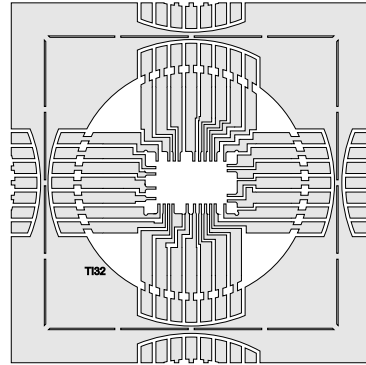


EMBEDDED

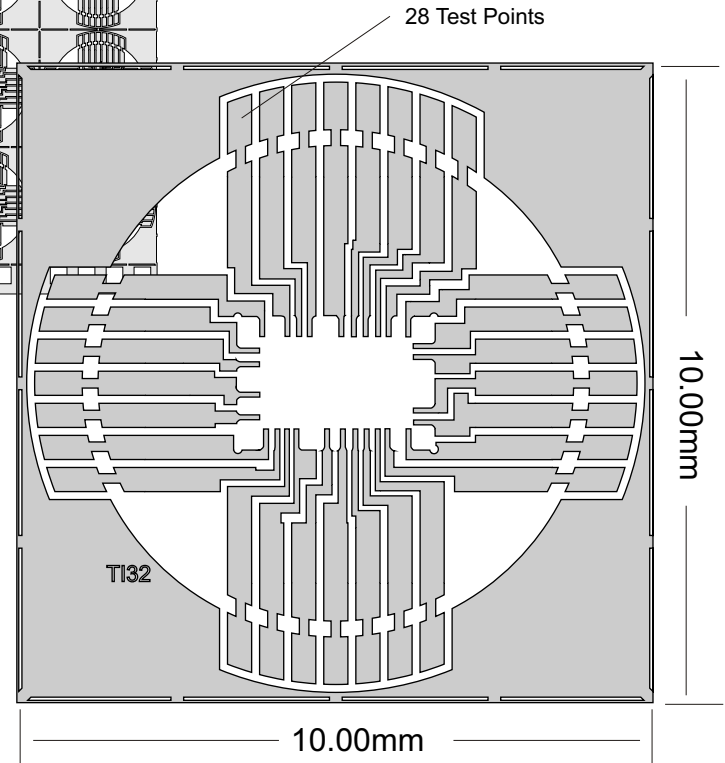
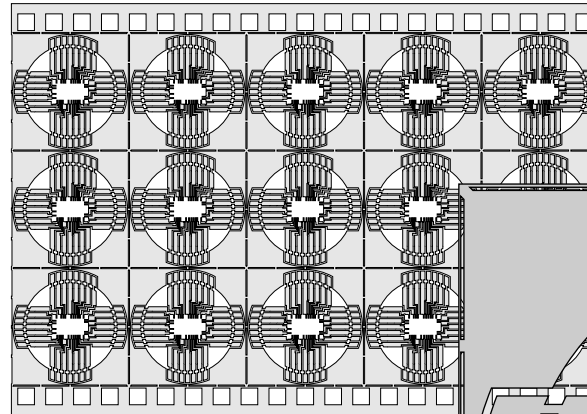
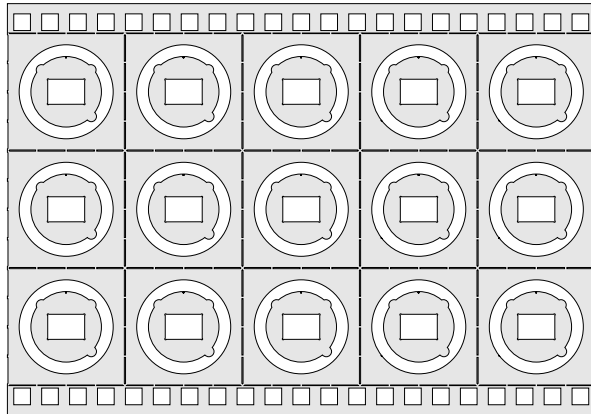
A MicroFlange™ component may be placed in the innerlayer of a multi level substrate and plated into the circuit interconnect



BOTTOM



TOP



Notes:

- a. TI MSP430F test frame 35mm format
- b. Independent test verification before exercise
- c. 30µin electroless Au finish